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				First Named Inventor	Scott E. Moore
				Group Art Unit	3723
				Examiner Name	Dung V. Nguyen
Sheet	1	of	1	Attorney Docket No.	108298515US

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document
		NUMBER	Kind Code (if known)		
DVN	AA	U.S. Patent Application Publication No. US 2002/0025763-A1		Lee et al.	02/28/2002
	AB	U.S. Patent Application Publication No. US 2002/0025759-A1		Lee et al.	02/28/2002
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		Office	NUMBER		

OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.			
DVN	AG	KONDO, S. et al., "Abrasive-Free Polishing for Copper Damascene Interconnection," <i>Journal of the Electrochemical Society</i> , Vol. 147, No. 10, pp. 3907-3913, The Electrochemical Society, Inc., Pennington, New Jersey, 2000.			
DVN	AH	McGraw-Hill, <i>Concise Encyclopedia of Science & Technology</i> , Sybil P. Parker, Editor in Chief, Fourth Edition, p. 367, McGraw-Hill, New York, New York, 1998.			

EXAMINER <i>Dung V. Nguyen</i>	DATE CONSIDERED 4-21-2003
*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).	